

ABSTRACT OF THE DISCLOSURE

INSPECTION DEVICE, MOUNTING APPARATUS, INSPECTION METHOD, AND PROGRAM

An inspection device includes: a measurement part, measuring a reference position of a mounting section before mounting of a semiconductor chip, a reference position of a plurality of peripheral sections located around the mounting section, and a position of the semiconductor chip after mounting; and an inspection part, based on a distance between the reference position of the mounting section and the reference position of the plurality of peripheral sections measured by the measurement part and a distance between the reference position of the plurality of peripheral sections and a mounting position of the semiconductor chip after mounting of the semiconductor chip, inspecting a relative position of the semiconductor chip with respect to the mounting section. Such an inspection device is able to accurately inspect the mounting position of the semiconductor chip.

Representative drawing: FIG. 5